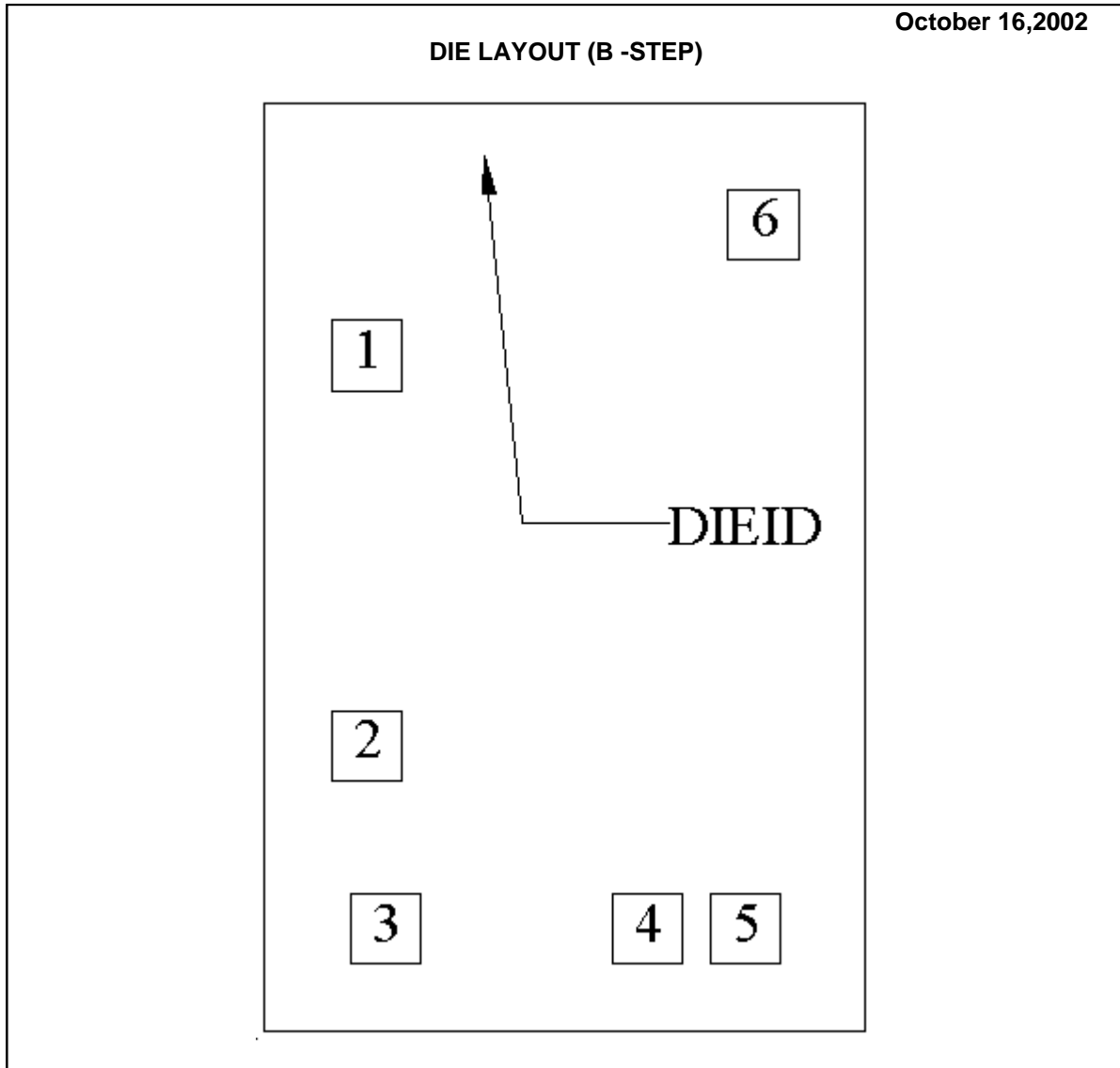


**LM2665 MDA MWA**  
**SWITCHED CAPACITOR VOLTAGE CONVERTER**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	LM2665B	Bond Pad Opening Size (min)	92μm x 92μm
Die Step	B	Bond Pad Metalization	0.5% COPPER, 1% SILICON, BAL. ALUMINUM, DLM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1219μm x 787μm 48mils x 31mils	Back Side Connection	OUTPUT
Thickness	216μm Nominal		
Min Pitch	128μm Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection						
SIGNAL	PAD#	X/Y CORRDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
CAP+	1	-260	278	92	x	92
OUTPUT	2	-260	-234	92	x	92
SD	3	-235	-474	92	x	92
GND	4	108	-474	92	x	92
CAP -	5	236	-474	92	x	92
V+	6	260	450	92	x	92

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**IN U.S.A.**

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Fax: 1 207 541 6140

**IN EUROPE**

Tel: 49 (0) 8141 351492 / 1495  
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